Technical Article Choosing Buck Converters and LDOs for Miniature Industrial Automation Equipment



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As the factory automation and control equipment market evolves, shipments of equipment with sensors such as field transmitters, machine vision and position sensors are increasing. As a result, the demand for feature-rich power integrated circuits (ICs) that could power these devices is also growing.

Figure 1 shows a block diagram of a temperature transmitter. The nonisolated power-supply subsystem (highlighted in red) consists of a low dropout regulator (LDO), a DC/DC converter or a power module. In an earlier technical article, "Powering tiny industrial automation control equipment with high-voltage modules: how to ensure reliability," my colleague Akshay Mehta explained how to power miniature industrial automation control equipment with high-voltage modules. In this article, I'll take a look at how to use buck converters and LDOs for the same purpose.



Figure 1. Temperature Transmitter Subsystem

High Input Voltage, Higher Stakes

There are a number of ways to regulate the input DC voltage in factory automation and control equipment. You can use an LDO, a DC/DC converter or a power module. LDOs such as the TPS7A47 are commonly used in

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sensor power supplies due to their simple design and ability to attenuate input noise and deliver a ripple-free output voltage. DC/DC converters are a good choice for applications operating at lower output voltages, higher input voltages or higher output currents. For example, the LMR36503 and LMR36506 DC/DC converters enable a low shutdown current specification of 1 μ A and an operating quiescent current specification of 7 μ A. For loads with low output currents – less than 20 mA – these performance specifications ensure higher efficiency for 4- to 20-mA loop applications. Figure 2 shows the efficiency and thermal performance of the LMR36506 converter.





Figure 2. Efficiency and Thermal Performance at 24 $v_{\text{IN}},$ 5 $V_{\text{OUT}},$ 2.1 Mhz at 0.6A

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Big Challenge, Small Solution

TPSM265R1 LMR36503 LMR36506 IN OUT



Figure 3. LMR36506 Example Solution Size

Lowering EMI, Raising the Standard





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LMR36503 LMR36506

Traditional wire-bond QFN package HotRod FCOL package Copper/gold/aluminum bond wires connect IC to pins Die is flipped and placed directly onto the leadframe ⇒ high package parasitic resistance and inductance ⇒ low package parasitic resistance and inductance ⇒ higher density, smaller package Mold compound Mold compound Cu/Au/Al DC/DC Converter IC (Silicon Die) Copper post bond wire DC/DC Converter IC (Silicon Die) Solder (Sn-Ag) Die Attach Exposed Thermal Pad Leadframe Solder Solder PCB (b) (a)

Figure 5. Wire-bond Quad Flat No-lead and FCOL Packages

Conclusion

LMR36506

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Additional Resources:

• If you're considering using modules to power your solution, read our technical article: Powering tiny industrial automation control equipment with high-voltage modules: how to ensure reliability

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